

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t8304hs8e-1#trpbf

(Engineering Calculation)

SOIC Exposed Pad

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**TOTAL MASS (g) : 0.074998**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002750	1000000	36667.6914062		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023398	964450	311982.03125		
		Iron (Fe)	7439-89-6	0.000547	22560	7293.53613281		
		Phosphorus (P)	7723-14-0	0.000006	240	80.0022354126		
		Zinc (Zn)	7440-66-6	0.000030	1250	400.011138916		
		Nickel (Ni)	7440-02-0	0.000279	11500	3720.10375977		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.024260</b>	<b>1000000</b>	<b>323475.6875</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001920	1000000	25599.4824219		
		<b>External Plating Total:</b>				<b>0.001920</b>	<b>1000000</b>	<b>25599.4824219</b>
		Inter. Plating Ni	7440-02-0	0.000300	1000000	4000.11157227		
		Inter. Plating Ag	7440-22-4	0.000000	0	0		
<b>Internal Plating Total:</b>				<b>0.000300</b>	<b>1000000</b>	<b>4000.11157227</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000902	750000	12027.0019531		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000301	250000	4013.4453125		
<b>Die Attach Total:</b>				<b>0.001203</b>	<b>1000000</b>	<b>16040.4462891</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.004571	103000	60948.3671875		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.039720	895000	529614.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000089	2000	1186.69970703		
		<b>Encapsulation Total:</b>				<b>0.044380</b>	<b>1000000</b>	<b>591749.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000185	1000000	2466.73535156		
					<b>TOTAL MASS (g) :</b>	<b>0.074998</b>		